



MULTILAYER CERAMIC CAPACITORS

Capacitor Arrays Series (10V to 100V)

4 x 0402, 4 x 0603 Sizes

NP0, X7R & Y5V Dielectrics

Halogen Free & RoHS Compliance

*Contents in this sheet are subject to change without prior notice.



1. INTRODUCTION

WTC middle and high voltage series MLCC is designed by a special internal electrode pattern, which can reduce voltage concentrations by distributing voltage gradients throughout the entire capacitor. This special design also affords increased capacitance values in a given case size and voltage rating.

WTC capacitor arrays are developed to offer designers the opportunity to lower placement costs increase assembly line output through lower component count per board.

2. FEATURES

- a. High density mounting due to mounting space saving.
- b. Mounting cost saving.
- c. Increased throughput.

3. APPLICATIONS

- a. For use as a bypass for digital and analog signal line noise
- b. Computer motherboards and peripherals.
- c. The other common electronic circuits.

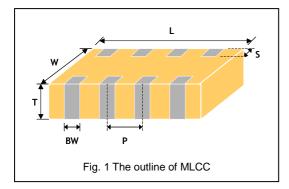
4. HOW TO ORDER

<u>Y</u>	<u>4C</u>	<u>3</u>	B	<u>103</u>	K	<u>500</u>	<u>C</u>	I
<u>Series</u>	Cap. Nr.	Termination pitch	Dielectric	Capacitance	Tolerance	Rated voltage	Termination	Packaging
Y =Capacitor array	4C =4xCap	3 =0.03" pitch* 2 =0.02" pitch*	N =NP0 (C0G)	Two significant digits followed	J =±5% K =±10%	Two significant digits followed	C =Cu/Ni/Sn	T =7" reeled
		8	B=X7R F=Y5V	by no. of zeros. And R is in place of	Z =-20/+80%	by no. of zeros. And R is in place of decimal		
	′4C3: 4x060 ′4C2: 4x040	6	Val SIN	decimal point. eg.:	iter i	point.		
			ALSN T	103=10x10 ³ =10,000pF	Colo	100=10 VDC 160=16 VDC		
			100	HIGLOGY CORP	RAILUN	250=25 VDC 500=50 VDC 101=100 VDC		

*Size/ Inch (mm) : 4x0402=0508 (1220), 4x0603=0612 (1632)



5. EXTERNAL DIMENSIONS



Size Inch (mm)	L (mm)	W (mm)	nm) T (mm)/Sym		S (mm)	BW (mm)	P (mm)
4x0402 0508 (1220)	2.00±0.15	1.25±0.15	0.85±0.10	т	0.20±0.10	0.25±0.10	0.50±0.10
4x0603 0612 (1632)	3.20±0.15	1.60±0.15	0.80±0.10	В	0.30±0.20	0.40±0.15	0.80±0.15

Reflow soldering process only.

6. GENERAL ELECTRICAL DATA

	12/1/7							
Dielectric	N N	P0		X7R				
Size	4x0402	4x0603	4x0402	4x0603	4x0603			
nch (mm)	0508 (1220)	0612 (1632)	0508 (1220)	0612 (1632)	0612 (1632)			
Capacitance*	10pF to 270pF	=10pF to 470pF	1000pF to 100nF	150pF to 100nF	10nF to 100nF			
Capacitance tolerance**	J (±5%),	K (±10%)	K (±10%),	Z (-20/+80%)				
Rated voltage (WVDC)	25, 50	V, 100V	10V, 16V, 25V, 50V	16V, 50V				
Q/Tan δ*	11/a	Q≥400+20C F: Q≥1000	Ur=50V Ur=25V&1 Ur=10V	Ur=50V, ≤5% Ur=16V, ≤7%				
Insulation resistance at Ur	≥10	OGO ANNOV CON	≥10GΩ	or RxC≥500ΩxF whic	chever is less			
Operating temperature			o +125℃	-25 to +85℃				
Capacitance characteristic	±30)ppm	±1	+30/-80%				
Termination			Ni/Sn (lead-free term	nination)				

* Measured at 30~70% related humidity.

NP0: Apply 1.0±0.2Vrms, 1.0MHz±10% at the conditions of 25°C ambient temperature.

X7R: Apply 1.0±0.2Vrms, 1.0kHz±10%, at the conditions of 25℃ ambient temperature.

Y5V: Apply 1.0±0.2Vrms, 1.0kHz±10%, at the conditions of 20°C ambient temperature.

** Preconditioning for Class II MLCC: Perform a heat treatment at 150±10°C for 1 hour, then leave in a mbient condition for 24±2 hours before measurement.

Approval Sheet

7. CAPACITANCE RANGE

	SIZE Inch (mm)			0	4 x 040 508 (12					4x0603 0612 (1632)						
	DIELECTRIC		NP0		X7R			NP0 X7R					Y5V			
RAT	RATED VOLTAGE		50	100	10	16	25	50	25	50	100	16	25	50	16	50
	(VDC)	T	т	т						В						
	10pF (100)	T T	T T	T T					B	B	B					
	15pF (150)	T	T	T					В	B	В					
	22pF (220) 33pF (330)	T	T	T					B	B	В					
	47pF (470)	T	T	T					B	B	В					
	68pF (680)	T	T	T					B	B	В					
	100pF (101)	T	T	T					B	B	B				1	
	120pF (121)	T	T	T					B	B	B					
	150pF (151)	T	Т	T					B	B	B		В	В	 	
	180pF (181)	T	Т	T					B	B	B		B	B		
	220pF (221)		Т	T					B	B	B		B	B		
	270pF (271)	T	T	T					В	B	B		B	B		
8	330pF (331)		· ·	· ·					B	B	B		B	B		
tan	470pF (471)								B	B	B		B	B		
aci	6,80pF (681)												B	B		
Capacitance	1,000pF (102)				Т	Т	A. 7	ΞT	1-				В	В		
Ŭ	1,500pF (152)				Т	.EE	PH	Т		SE.			В	В		
	2,200pF (222)				T,	/, T.Š	Jr.	财子	X	S)	1		В	В	1	
	3,300pF (332)				τN	ँ र	<u>\</u> τ>		A,	20	Tal		В	В		
	4,700pF (472)				A. 17	J.	Т	Т		¥	72		В	В	1	
	6,800pF (682)				Ť	J.T.S	Т	Т		∇	6		В	В		
	0.010µF (103)				Т	₩#/	T	T			7		В	В		В
	0.015µF (153)				Т	Т	Т	N	A			В	В	В		В
	0.022µF (223)				đ	TPA	ssitve	SYSTEM	ALLIA	NCE		В	В	В		В
	0.033µF (333))M	ZT∖	Т			7 .3		В				В
	0.047µF (473)				T	्र	Т				13	В				В
	0.068µF (683)				T	T I	Т			0	5	В				В
	0.10µF (104)				T	Т	O.T.		60	12 6	S	В			В	В

1. The letter in cell is expressed the symbol of product thickness.

8. PACKAGING DIMENSION AND QUANTITY

SIZE	Thickness/Syr	nbol	Paper tape				
Inch (mm)	(mm)		7" reel	13" reel			
4x0402	0.85±0.10	т	4k	-			
0508 (1220)	0.0010.10						
4x0603	0.80±0.10	В	4k	-			
0612 (1632)	0.00±0.10	В	4K				

Unit: pieces



9. RELIABILITY TEST CONDITIONS AND REQUIREMENTS

No.	ltem	Test Condition	Requirements					
1.	Visual and		* No remarkable defect.					
	Mechanical		* Dimensions to conform to individual specification sheet.					
2.	Capacitance	Class I: (NP0)	* Shall not exceed the limits given in the detailed spec.					
3.	Q/ D.F.	1.0±0.2Vrms, 1MHz±10%	NP0: Cap≥30pF, Q≥1000; Cap<30pF, Q≥400+20C					
	(Dissipation	Class II: (X7R, Y5V)	X7R: Ur=50V, ≤2.5%; Ur=25V&16V, ≤3.5%; Ur=10V, ≤5.0%					
	Factor)	1.0±0.2Vrms, 1kHz±10%	Y5V: Ur=50V, ≤5%; Ur=16V, ≤7%					
		*Before initial measurement (Class II only): To apply de-aging						
		at 150°C for 1hr then set for 24 \pm 2 hrs at room temp.						
4.	Dielectric	* To apply 250% rated voltage.	* No evidence of damage or flash over during test.					
	Strength	* Duration: 1 to 5 sec.						
		* Charge and discharge current less than 50mA.						
5.	Insulation	To apply rated voltage for max. 120 sec.	≥10GΩ or RxC≥500Ω-F whichever is smaller.					
	Resistance	*Before initial measurement (Class II only): To apply de-aging						
		at 150°C for 1hr then set for 24 \pm 2 hrs at room temp .						
6.	Temperature	With no electrical load.						
	Coefficient	T.C. Operating Temp	T.C. Capacitance Change					
		NP0 -55~125℃ at 25℃	NP0 Within ±30ppm/℃					
		X7R -55~125°C at 25°C	X7R Within ±15%					
		Y5V -25~85°C at 20°C	Y5V Within +30%/-80%					
		*Before initial measurement (Class II only): To apply de-aging						
-		at 150°C for 1hr then set for 24±2 hrs at room temp.						
	Adhesive	* Pressurizing force :	* No remarkable damage or removal of the terminations.					
	-	5N (≤0603) and 10N (>0603)						
	Termination	* Test time: 10±1 sec.						
8.	Vibration	* Vibration frequency: 10~55 Hz/min.	* No remarkable damage.					
	Resistance	* Total amplitude: 1.5mm PASSIVE SYSTEM ALI	* Cap change and Q/D.F.: To meet initial spec.					
		* Test time: 6 hrs. (Two hrs each in three mutually						
		perpendicular directions.)						
		*Before initial measurement (Class II only): To apply de-aging at 150° for 1hr then set for 24 ± 2 hrs at room temp.						
		*Cap./DF(Q) Measurement to be made after de-aging at 150°C	0, 183					
		for 1hr then set for 24±2 hrs at room temp.	CON Alle					
9.	Solderability	* Solder temperature: 235±5℃	95% min. coverage of all metalized area.					
5.	Solderability	* Dipping time: 2±0.5 sec.	so with coverage of an metalized area.					
10	Bending Test	* The middle part of substrate shall be pressurized by means	* No remarkable damage.					
	Soluting 1631	of the pressurizing rod at a rate of about 1 mm per second until						
		the deflection becomes 1 mm and then the pressure shall be	NP0: within ±5.0% or ±0.5pF whichever is larger.					
		maintained for 5 ± 1 sec.	X7R: within $\pm 12.5\%$					
		*Before initial measurement (Class II only): To apply de-aging	Y5V: within ±30%					
		at 150°C for 1hr then set for 24 \pm 2 hrs at room temp .	(This capacitance change means the change of capacitance under					
		*Measurement to be made after keeping at room temp. for	specified flexure of substrate from the capacitance measured before					
		24±2 hrs.	the test.)					
11.	Resistance to	* Solder temperature: 260±5℃	* No remarkable damage.					
	Soldering Heat		* Cap change:					
	_	* Preheating: 120 to 150°C for 1 minute before imme rse the	NP0: within ±2.5% or ±0.25pF whichever is larger.					
		capacitor in a eutectic solder.	X7R: within ±7.5%					
		*Before initial measurement (Class II only): To apply de-aging	Y5V: within ±20%					
		at 150°C for 1hr then set for 24±2 hrs at room temp.	* Q/D.F., I.R. and dielectric strength: To meet initial requirements.					
		*Cap. / DF(Q) / I.R. Measurement to be made after de-aging at						
		150° for 1hr then set for 24±2 hrs at room temp.						

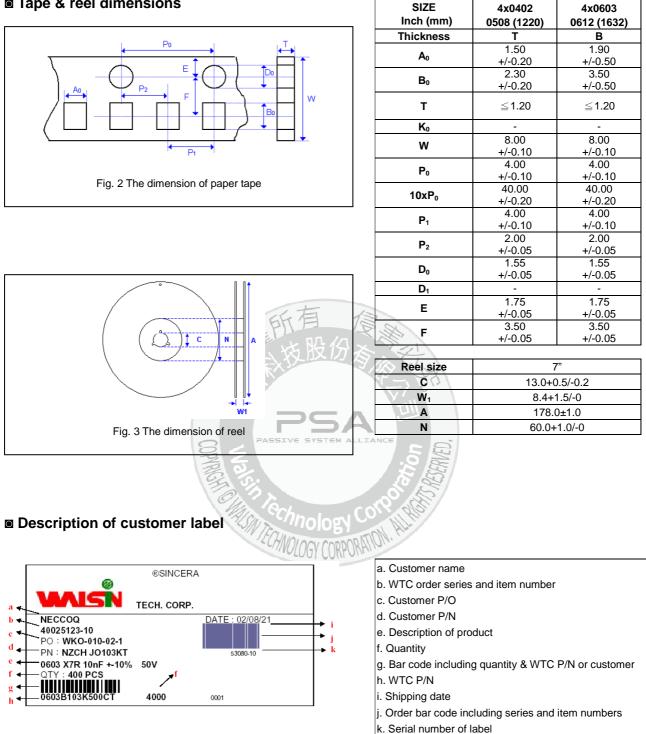


No.	ltem	Test Condition	Requirements
12.	Temperature Cycle	* Conduct the five cycles according to the temperatures and time. Step Temp. (°C) Time (min.) 1 Min. operating temp. +0/-3 30±3 2 Room temp. 2~3 3 Max. operating temp. +3/-0 30±3 4 Room temp. 2~3 *Before initial measurement (Class II only): To apply de-aging at 150°C for 1hr then set for 24±2 hrs at room temp . * Cap. / DF(Q) / I.R. Measurement to be made after de-aging at 150°C for 1hr then set for 24±2 hrs at room temp .	
13.	Humidity (Damp Heat) Steady State	 * Test temp.: 40±2°C * Humidity: 90~95% RH * Test time: 500+24/-0hrs. *Before initial measurement (Class II only): To apply de-aging at 150°C for 1hr then set for 24±2 hrs at room temp. * Cap. / DF(Q) / I.R. Measurement to be made after de-aging at 150°C for 1hr then set for 24±2 hrs at room temp. 	Y5V: within ±30%
14.	Humidity (Damp Heat) Load	 * Test temp.: 40±2°C * Humidity: 90~95%RH * Test time: 500+24/-0 hrs. * To apply voltage : rated voltage. *Before initial measurement (Class II only): To apply de-aging at 150°C for 1hr then set for 24±2 hrs at room temp. * Cap. / DF(Q) / I.R. Measurement to be made after de-aging at 150°C for 1hr then set for 24±2 hrs at room temp. 	NP0: Cap≥30pF, Q≥200; Cap<30pF, Q≥100+10/3C
15.	High Temperature Load (Endurance)	 * Test temp.: NP0, X7R: 125±3°C Y5V: 85±3°C * To apply voltage: 200% of rated voltage. * Test time: 1000+24/-0 hrs. * Before initial measurement (Class II only): To apply de-aging at 150°C for 1hr then set for 24±2 hrs at room temp . * Cap. / DF(Q) / I.R. Measurement to be made after de-aging at 150°C for 1hr then set for 24±2 hrs at room temp . 	10pF≤Cap<30pF, Q≥275+2.5C

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APPENDIXES

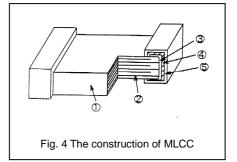
Tape & reel dimensions



Approval Sheet

Constructions

No.	Nam	ie	NP0, X7R, Y5V
1	Ceramic r	naterial	BaTiO₃ based
2	Inner ele	ctrode	Ni
3		Inner layer	Cu
4	Termination	Middle layer	Ni
5		Outer layer	Sn (Matt)



Approval Sheet

Storage and handling conditions

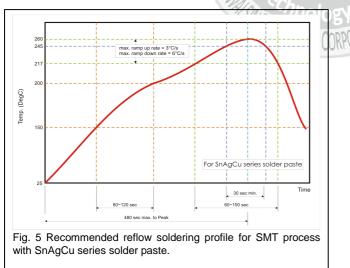
- (1) To store products at 5 to 40°C ambient temperature and 20 to 70%. related humidity conditions.
- (2) The product is recommended to be used within one year after shipment. Check solderability in case of shelf life extension is needed.

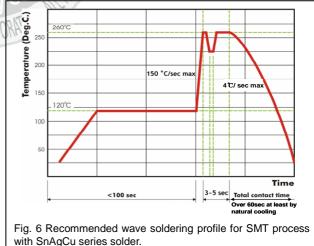
Cautions:

- a. The corrosive gas reacts on the terminal electrodes of capacitors, and results in the poor solderability. Do not store the capacitors in the ambience of corrosive gas (e.g., hydrogen sulfide, sulfur dioxide, chlorine, ammonia gas etc.)
- b. In corrosive atmosphere, solderability might be degraded, and silver migration might occur to cause low reliability.
- c. Due to the dewing by rapid humidity change, or the photochemical change of the terminal electrode by direct sunlight, the solderability and electrical performance may deteriorate. Do not store capacitors under direct sunlight or dewing condition. To store products on the shelf and avoid exposure to moisture.

Recommended soldering conditions

The lead-free termination MLCCs are not only to be used on SMT against lead-free solder paste, but also suitable against lead-containing solder paste. If the optimized solder joint is requested, increasing soldering time, temperature and concentration of N_2 within oven are recommended.





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 DF18141950B102T
 DB18142140B102T
 SF14112450A03T
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 WF08U1002BTL

 1206N392J500CT
 RFCBA040310IM6B301
 WF06U1002BTL
 WF12P2200FTL
 WF06R2002BTL
 WF08P8202FTL
 WK12V105
 JTL

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 0805N102J501CT
 WW25WR025FTL
 1206B564K500CT
 WF08U8251BTL
 RFBLN06051G8D1T
 0603B683K101CT

 WR02X2202FAL
 1812B225K500CT
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 1812B824K251CT
 1210F107Z6R3CT
 0603N102F500CT
 YU0AS102M080DAMD0B

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 WF25P1001FTL
 WLPN303015M470PB
 1206B683K201
 WR25X361JTL
 WR25X1R8JTL
 YP1AH471K070BAMD0H

 1206N470J102LT
 1206B473K251CT
 WK12V155 JTL
 1206B184K101CT
 SH32B225K101CT
 RFCBA100607SA6B701
 0603N510J500CT

 1812B472K202CT
 WK12V155
 JTL
 1206B184K101CT
 SH32B225K101CT
 RFCBA100607SA6B701
 0603N510J500CT